

Silicon Carbide Power Schottky Diode

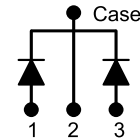
V_{RRM}	=	1200 V
$I_F (T_C = 25^\circ\text{C})$	=	24 A **
$I_F (T_C \leq 150^\circ\text{C})$	=	10 A **
Q_C	=	21 nC *

Features

- Industry's leading low leakage currents
- 175 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of V_F
- Extremely fast switching speeds
- Superior figure of merit Q_C/I_F

Package

- RoHS Compliant


TO – 247


Advantages

- Low standby power losses
- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Low reverse recovery current
- Low device capacitance
- Low reverse leakage current at operating temperature

Applications

- Power Factor Correction (PFC)
- Switched-Mode Power Supply (SMPS)
- Solar Inverters
- Wind Turbine Inverters
- Motor Drives
- Induction Heating
- Uninterruptible Power Supply (UPS)
- High Voltage Multipliers

Maximum Ratings at $T_j = 175^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current (Per Leg/Device)	I_F	$T_C = 25^\circ\text{C}$	12/24	A
Continuous forward current (Per Leg/Device)	I_F	$T_C \leq 150^\circ\text{C}$	5/10	A
RMS forward current (Per Leg/Device)	$I_{F(RMS)}$	$T_C \leq 150^\circ\text{C}$	8/16	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$	32	A
		$T_C = 150^\circ\text{C}, t_p = 10\text{ ms}$	26	
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ }\mu\text{s}$	120	A
I^2t value	$\int j^2 dt$	$T_C = 25^\circ\text{C}, t_p = 10\text{ ms}$	5	A^2s
		$T_C = 150^\circ\text{C}, t_p = 10\text{ ms}$	3.4	
Power dissipation (Per Leg/Device)	P_{tot}	$T_C = 25^\circ\text{C}$	117/234	W
Operating and storage temperature	T_j, T_{stg}		-55 to 175	$^\circ\text{C}$

Electrical Characteristics at $T_j = 175^\circ\text{C}$, unless otherwise specified (Per Leg)

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	V_F	$I_F = 5\text{ A}, T_j = 25^\circ\text{C}$		1.6	1.9	V
		$I_F = 5\text{ A}, T_j = 175^\circ\text{C}$		2.6	3.0	
Reverse current	I_R	$V_R = 1200\text{ V}, T_j = 25^\circ\text{C}$		5	50	μA
		$V_R = 1200\text{ V}, T_j = 175^\circ\text{C}$		10	100	
Total capacitive charge	Q_C	$I_F \leq I_{F,MAX}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $T_j = 175^\circ\text{C}$	$V_R = 400\text{ V}$	21		nC
	$V_R = 960\text{ V}$		35			
Switching time	t_s		$V_R = 400\text{ V}$ $V_R = 960\text{ V}$	< 25		ns
Total capacitance	C	$V_R = 1\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		260		pF
		$V_R = 400\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		25		
		$V_R = 1000\text{ V}, f = 1\text{ MHz}, T_j = 25^\circ\text{C}$		20		

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}	1.4 *	$^\circ\text{C}/\text{W}$
-------------------------------------	------------	-------	---------------------------

Mechanical Properties

Mounting torque	M	0.6	Nm
-----------------	---	-----	----

* Per Leg, ** Per Device

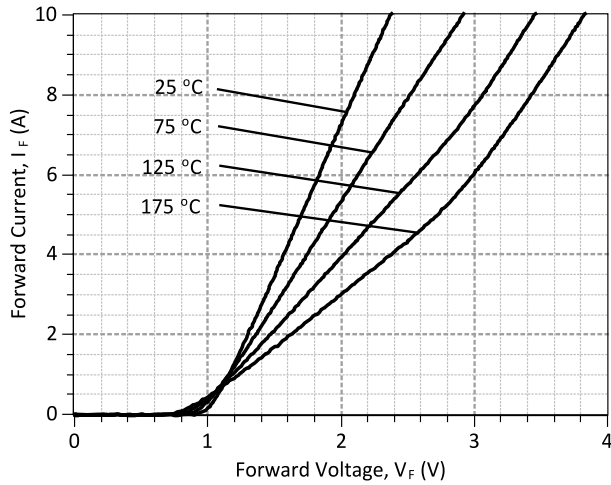


Figure 1: Typical Forward Characteristics (Per Leg)

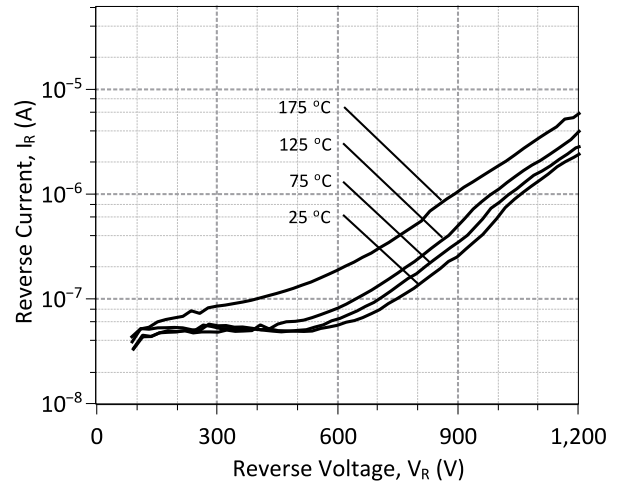


Figure 2: Typical Reverse Characteristics (Per Leg)

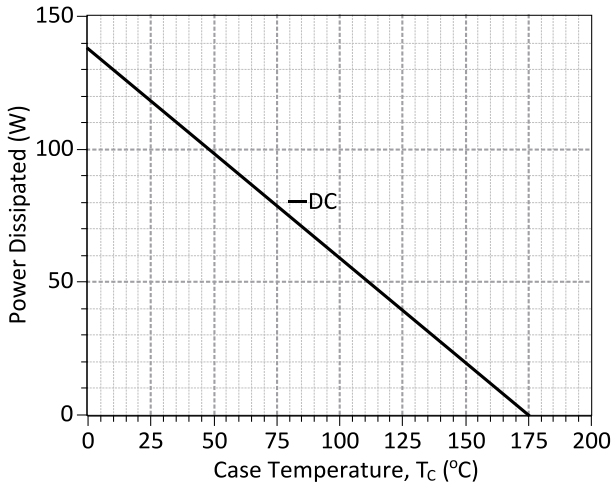


Figure 3: Power Derating Curve (Per Leg)

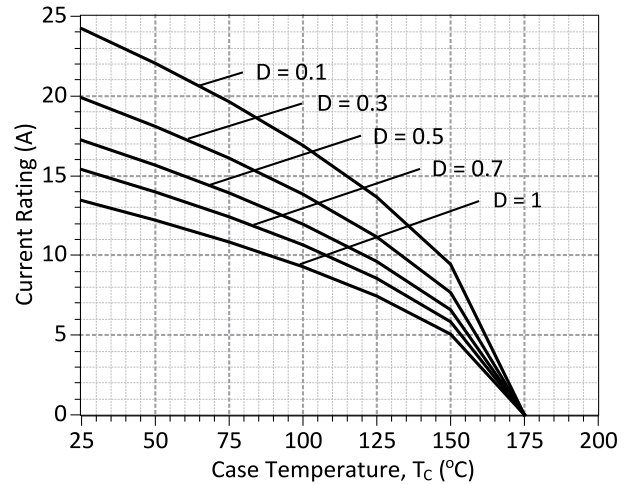


Figure 4: Current Derating Curves ($D = t_p/T$, $t_p = 400 \mu s$) (Considering worst case Z_{th} conditions) (Per Leg)

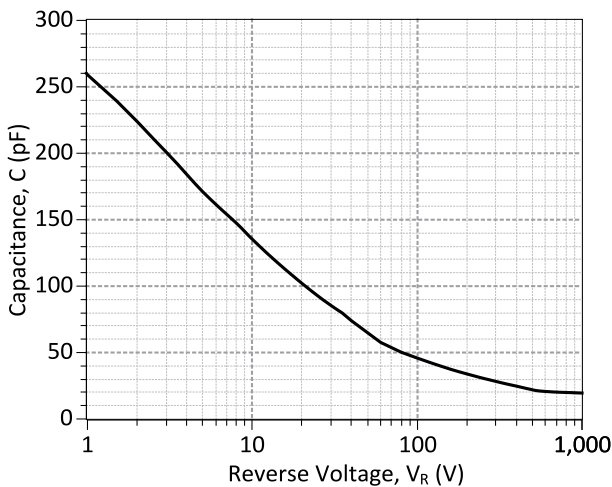


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics (Per Leg)

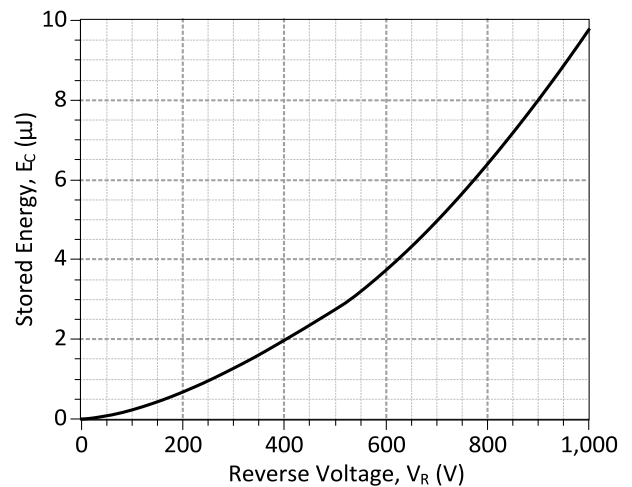


Figure 6: Typical Capacitive Energy vs Reverse Voltage Characteristics (Per Leg)

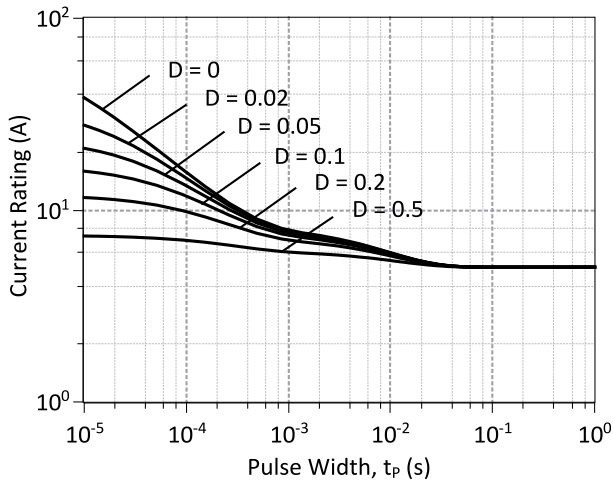


Figure 7: Current vs Pulse Duration Curves at $T_c = 155\text{ }^\circ\text{C}$ (Per Leg)

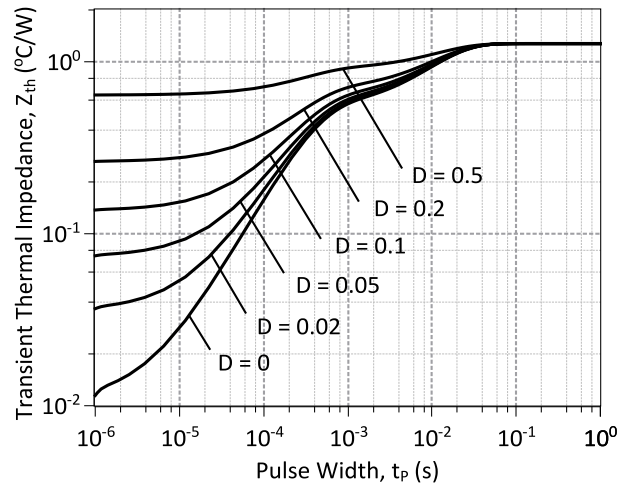
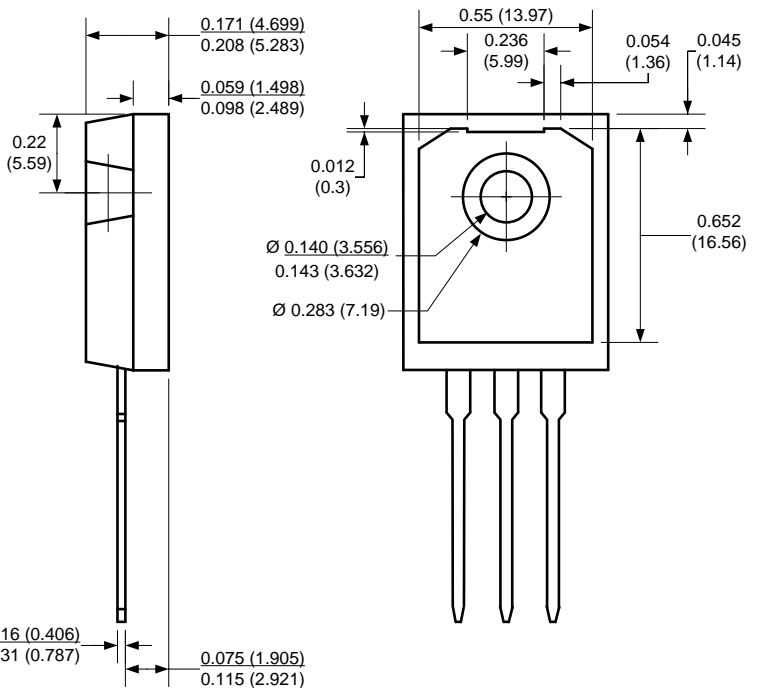
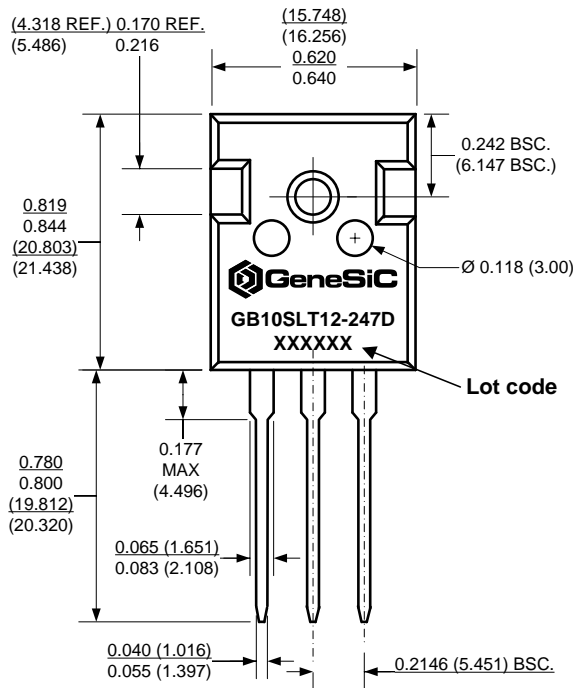


Figure 8: Transient Thermal Impedance (Per Leg)

Package Dimensions:

TO-247

PACKAGE OUTLINE



NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History

Date	Revision	Comments	
2015/09/16	0	Initial release	

Published by

GeneSiC Semiconductor, Inc.
43670 Trade Center Place Suite 155
Dulles, VA 20166

GeneSiC Semiconductor, Inc. reserves right to make changes to the product specifications and data in this document without notice.

GeneSiC disclaims all and any warranty and liability arising out of use or application of any product. No license, express or implied to any intellectual property rights is granted by this document.

Unless otherwise expressly indicated, GeneSiC products are not designed, tested or authorized for use in life-saving, medical, aircraft navigation, communication, air traffic control and weapons systems, nor in applications where their failure may result in death, personal injury and/or property damage.

SPICE Model Parameters

This is a secure document. Please copy this code from the SPICE model PDF file on our website (http://www.genesicsemi.com/images/products_sic/rectifiers/GB10SLT12-247D_SPICE.pdf) into LTSPICE (version 4) software for simulation of the GB10SLT12-247D. All the simulations are per Leg.

```

*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0           $
*      $Date:      16-SEP-2015   $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*
*      COPYRIGHT (C) 2015 GeneSiC Semiconductor Inc.
*      ALL RIGHTS RESERVED
*
* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
*
* Start of GB10SLT12-247D SPICE Model
*
.SUBCKT GB10SLT12D ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0015); Temperature Dependant Resistor
D1 INT KATHODE GB10SLT12D_25C; Call the 25C Diode Model
D2 ANODE KATHODE GB10SLT12D_PIN; Call the PiN Diode Model
.MODEL GB10SLT12D_25C D
+ IS      5.83E-18      RS      0.1276
+ N       1            IKF     602
+ EG      1.2          XTI     3
+ CJO     3.00E-10     VJ     0.419
+ M       1.6          FC     0.5
+ TT      1.00E-10     BV     1200
+ IBV     1.00E-03     VPK     1200
+ IAVE    5            TYPE    SiC_Schottky
+ MFG     GeneSiC_Semiconductor
.MODEL GB10SLT12D_PIN D
+ IS      3.50 E-12     RS      0.3648
+ N       4.409        IKF     73
+ EG      3.23         XTI     -6
+ FC      0.5          TT     0
+ BV      1200         IBV     1.00E-03
+ VPK     1200         IAVE    1
+ TYPE    SiC_PiN
.ENDS
*
* End of GB10SLT12-247D SPICE Model

```



Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

Наши контакты:

Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург,
Промышленная ул, дом № 19, литера Н,
помещение 100-Н Офис 331